nexperia

Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

| Supplier | | User Part Number | | | | | |
|-------------------------------------|-----------------------------|---|-----------------------|-----------|------------|-----------|--|
| Nexperia B.V. Name of Laboratory | | PESD3V3S2UAT Part Description | | | | | |
| | | | | | | | |
| Assembly reliability labs | | SMD package | | | | | |
| Based on AEC-Q101 Test | | Test Conditions | Duration | # Lots | # Quantity | # Rejects | |
| | TEST | | | | | | |
| | Pre- and Post-Stress | | | | | | |
| # E1 | Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below | |
| | | JESD22-A113 | | | | | |
| | PC | Bake Tamb = 125 °C | 24 hours 168 hours | | | | |
| # A1 | Preconditioning | Soak Tamb = 85 °C, RH = 85% Reflow soldering | 3 cycles | 286 | 21480 | 0 | |
| # A1 | Treconditioning | - | 5 cycles | 280 | 21480 | 0 | |
| | HTRB | MIL-STD-750-1 M1038 Method A | | | | | |
| | | Tj = Tjmax, Vr = 100% of max. datasheet | | | | | |
| # B1 | Bias | reverse voltage | 1000 hours | 117 | 9360 | 0 | |
| # DI | 5100 | letere totage | 1000 110013 | 11/ | 9500 | 0 | |
| | тс | JESD22-A104 | | | | | |
| # A4 | Temperature Cycling | -65 °C to Tjmax, not to exceed 150°C | 1000 cycles | 86 | 6880 | 0 | |
| | | JESD22-A102 | | | | - | |
| | AC | Tamb = $121 ^{\circ}C$, RH = $100 ^{\circ}M$ | | | | | |
| # A3 alt | Autoclave | Pressure = 205 kPa (29.7 psia) | 96 hours | 86 | 6880 | 0 | |
| | | | | | | | |
| | H3TRB | JESD22-A101 | | | | | |
| | High Humidity High | Tamb = 85 °C, RH = 85%, VR = 80 % of | | | | | |
| # A2 alt | Temperature Reverse Bias | rated reverse voltage ^[1] | 1000 hours | 86 | 6880 | 0 | |
| | | MIL-STD-750 Method 1037 | | | | | |
| | IOL | ton = toff, devices powered to insure ΔTj = | | | | | |
| # A5 | Intermittent Operating Life | 100 °C for 15000 cycles | 1000 hours | n.a. | n.a. | n.a. | |
| | | | | | | | |
| | RSH | JESD22-A111 | | | | | |
| # C8 | Resistance to Solder Heat | 260 °C ± 5 °C | 10 s | 28 | 840 | 0 | |
| | SD | | | | | | |
| # C10 | Solderability | J-STD-002 | | 36 | 360 | 0 | |

[1]The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Fechnology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|------------|----------|---------|--------------------|------------|
| Protection | 9360 | 0 | 0.45 | 2.20E+09 |
| | | | | |

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